Jie Chen

List of Publications by Year
in descending order

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10 papers	85 citations	1684188 5 h-index	1474206 9 g-index
10 all docs	10 docs citations	10 times ranked	45 citing authors

#	Article	IF	Citations
1	Junction-to-Case Thermal Resistance Measurement and Analysis of Press-Pack IGBTs Under Double-Side Cooling Condition. IEEE Transactions on Power Electronics, 2022, 37, 8543-8553.	7.9	10
2	Study of IGBTs Reliability Under Coupled Electricalâ€“Thermal Environment. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2021, 9, 4260-4268.	5.4	10
3	The Distributed Heat Source Modeling Method for the Finite Element Simulation of IGBTs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 83-89.	2.5	5
4	Temperature Distribution Evaluation of Single Chip by Multiple Currents <i>V</i> _{CE} (<i>T</i>) Method. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 426-434.	2.5	3
5	Sequential <i>V</i> _{ce}(<i>T</i>) Method for the Accurate Measurement of Junction Temperature Distribution Within Press-Pack IGBTs. IEEE Transactions on Power Electronics, 2021, 36, 3735-3743.	7.9	17
6	Calibration Method of Junction Temperature Measurement for Press-Pack IGBTs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 1063-1072.	2.5	1
7	The Influence and Application of Bond Wires Failure on Electrothermal Characteristics of IGBT Module. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 1426-1434.	2.5	5
8	Investigation on the accuracy of the junction temperature determined by the VCE(T) method under different load pulse durations in power cycling test. Microelectronics Reliability, 2021, 127, 114420.	1.7	0
9	Investigations on Averaging Mechanisms of Virtual Junction Temperature Determined by <i>V</i> _{CE} (<i>T</i>) Method for IGBTs. IEEE Transactions on Electron Devices, 2020, 67, 1106-1112.	3.0	25
10	Influence of the clamping force on the power cycling lifetime reliability of press pack IGBT subâ€‘module. Journal of Engineering, 2019, 2019, 2435-2439.	1.1	9